

3. The display device according to claim 2 wherein said first layer is formed by applying a conductive paste over the glass substrate and then baking said conductive paste.

4. A display device comprising:

a glass substrate;

a lead formed over the glass substrate, said lead comprising a first layer comprising silver and a second layer comprising indium tin oxide formed on the first layer;

an IC chip provided over the glass substrate with an adhesive therebetween and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second layer of the lead,

wherein said adhesive comprises a resin and metal particles.

5. The display device according to claim 4 wherein said adhesive comprises an epoxy resin.

6. The display device according to claim 4 wherein said metal particles are Ni particles.

7. A display device comprising:

a glass substrate;

a lead formed over the glass substrate, said lead comprising a first conductive layer and a second conductive layer comprising indium tin oxide formed on the first layer;

an IC chip provided over the glass substrate with an adhesive therebetween and electrically connected to the lead wherein a pad of the IC chip is electrically connected to the second conductive layer of the lead,

wherein said adhesive comprises a resin and metal particles.